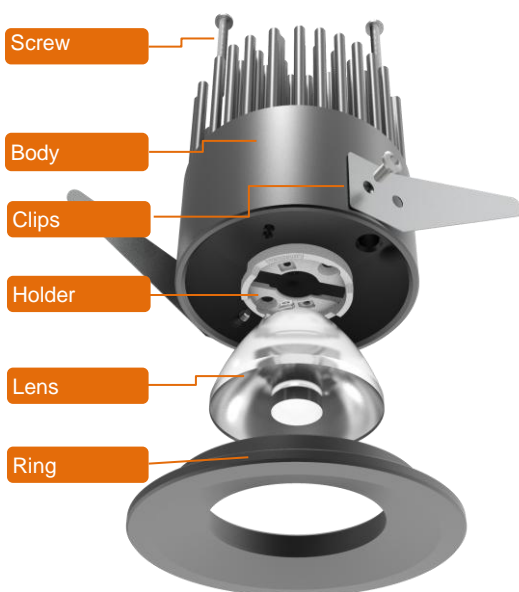


## Meng Meng-8065-B-xx Lighting Housing for COB Modular assembly & introduction

### Features & Benefits

- \* Mechanical compatibility with direct mounting of the COB products to the LED thermal body and thermal performance matching the lumen packages.
- \* For Down light designs from 500 to 1700 lumen.
- \* Thermal resistance range  $R_{th}$  2.75°C/W.
- \* Full accessory kit with LED cooler Body, PSU mounting shrapnel & lens holder.
- \* Other accessories like COB holder & lens separate available.
- \* Modular design with mounting holes foreseen for direct mounting of a wide range of LED modules and COB's.
- \* Forged from highly conductive aluminum.
- \* Diameter 80mm - Standard height 65mm, Other heights on request.
- \* standard colors Black anodised.



- 01) Bridelux: V6-G6,V8-G7,V10,H6,HD6 LED engines;
  - 02) Cree: XLamp CXA/CXB 13xx, XLamp CXA/CXB 15xx Series engines;
  - 03) Citizen: CLU701 LED engines;
  - 04) Luminus: CXM-3,CXM-4;CXM-6 LED engines;
  - 05) ECO: H4E,H6, S6D;
  - 06) Edison: EdiLex III 3w,6w,9w,12w COB LED engines;
  - 07) LG Innotek: L COB G1 Series 7w,10w,16w ;  
L COB G2 Series 6w,9w,12w,15w,18w ;F COB G1 Series 12w LED engines;
  - 08) LumiLEDs: LUXEON CoB 1202s, LUXEON COB 1202,1203 LED engines;
  - 09) Lumens: Ergon COB HO Series 1304,1507,1512,1517 LED engines;
  - 10) Nichia: NTCWT012B-V3,NTCWS024B-V3 Series LED engines;
  - 11) Prolight Opto: PACJ-7xxx/14xxx/21xxx/28xxx-xxxx engines;
  - 12) Samsung: LC010C/020C; LC003D/006/009;LC013/016D Series LED engines;
  - 13) Seoul: SAWxx661A;SAWxx64A;SAWxx063A,SAWxx64A Series COB LED engines;
- Note: 12.5x12.5mm LES4.0mm VS 13.5x13.5mm LES 6.0mm modules mounting holes for direct assembly of all LED COB brands**
- Need to match the 9mm LES COB , The beam Angle will be different.**

### Order Information

Example: Meng-8065-B-24

Soak-Meng-8055 - **1** - **2**

#### **1** Finish

- B-Black
- C-Clear
- Z-Custom

#### **2** Beam Angle

- |      |     |
|------|-----|
| - 10 | 10° |
| - 24 | 24° |
| - 34 | 34° |
| - 60 | 60° |

#### Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

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Http://www.mingfatech.com



## The product data table

	 <i>Meng Family</i>
<b>Model No.</b>	<b>Meng-8065-B-xx</b>
<b>Heatsink Size</b>	<b>Φ80×65.0mm</b>
<b>Beam Angle</b>	<b>10°/ 24°/ 34°/ 60°</b>
<b>Cut Out</b>	<b>Φ72.0-Φ75.0mm</b>
<b>Heatsink Material</b>	<b>AL1070</b>
<b>Heatsink Finish</b>	<b>Black anodised</b>
<b>Weight</b>	<b>230.0g</b>
<b>Lamp power (Ths-amb,40℃)</b>	<b>15.5 (w)</b>
<b>Thermal Resistance (Rhs-amb)</b>	<b>2.75(°C/W)</b>

\* 3D files are available in ParaSolid, STP and IGS on request

\* The thermal resistance  $R_{th}$  is determined with a calibrated heat source of 14mm×14mm central placed on the heat sink,  $T_{amb}$  40° and an open environment. Reference data @ heat sink to ambient temperature rise  $T_{hs-amb}$  50°C

The thermal resistance of a LED cooler is not a fix value and will vary with the applied dissipated power  $P_d$

\* Dissipated power  $P_d$ . Reference data @ heat sink to ambient temperature rise  $T_{hs-amb}$  50°C

The maximal dissipated power needs to be verified in function of required case temperature  $T_c$  or junction temperature  $T_j$  and related to the estimated ambient temperature where the light fixture will be placed Please be aware the dissipated power  $P_d$  is not the same as the electrical power  $P_e$  of a LED module

To calculate the dissipated power please use the following formula:  $P_d = P_e \times (1-\eta_L)$

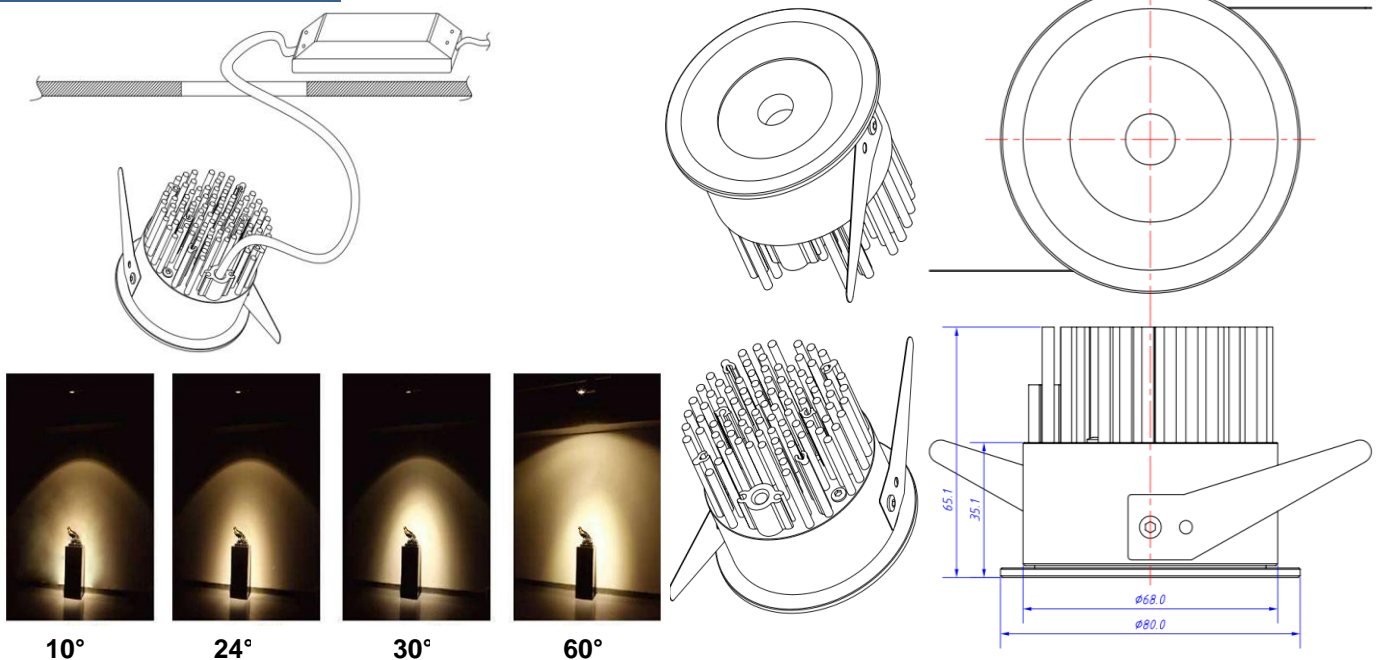
$P_d$  - Dissipated power

$P_e$  - Electrical power

$\eta_L$  = Light efficiency of the LED module

## Meng Meng-8065-B-xx Lighting Housing for COB Modular assembly & introduction

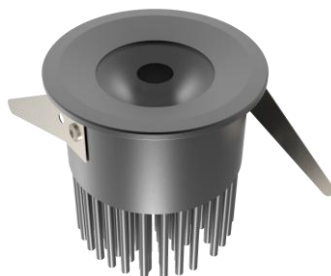
### Drawings & Type Selection



### Components introduction

1. Remove the Ring, Install the COB  
Fix the COB by the holder and screw

2. Fix the COB by the Lens and screw

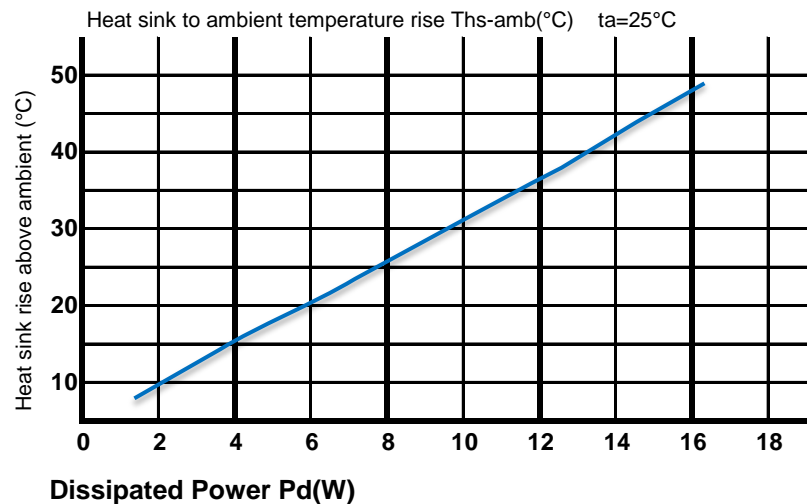


4. Vertically align the shrapnel and press down on the reflector assembly

3. Fix the Ring by the Lens and screw

**The thermal data table**

$P_d = P_e \times (1 - \eta_L)$		Heat sink to ambient thermal resistance $R_{hs-amb} (^{\circ}C/W)$	Heat sink to ambient temperature rise $\Delta T_{hs-amb} (^{\circ}C)$
<b>Meng-8065-B-xx</b>			
Dissipated Power $P_d(W)$	2	3.98	8
	4	3.68	14.8
	6	3.13	17.8
	8	3.14	25.3
	10	3.10	31.5
	12	2.98	36.2
	14	2.73	43.2



\* Please be aware the dissipated power  $P_d$  is not the same as the electrical power  $P_e$  of a LED module.

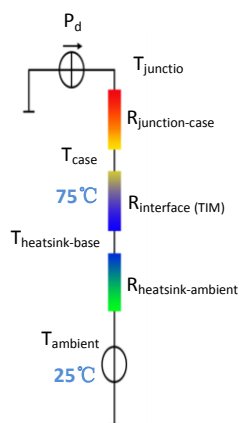
\*To calculate the dissipated power please use the following formula:  $P_d = P_e \times (1 - \eta_L)$ .

$P_d$  - Dissipated power ;  $P_e$  - Electrical power ;  $\eta_L$  = Light efficiency of the LED module;

\*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



\*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula:  $\theta = (T_{hs} - T_a) / P_d$

$\theta$  - Thermal Resistance [ $^{\circ}C/W$ ];  $T_{hs}$  - Heatsink temperature ;  $T_a$  - Ambient temperature ;

\*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is  $R_{junction-case}$ , the thermal resistance of the TIM outside the package is  $R_{interface (TIM)}$  [ $^{\circ}C/W$ ], the thermal resistance with the

heat sink is  $R_{heatsink-ambient}$  [ $^{\circ}C/W$ ], and the ambient temperature is  $T_{ambient}$  [ $^{\circ}C$ ].

\*Thermal resistances outside the package  $R_{interface (TIM)}$  and  $R_{heatsink-ambient}$  can be integrated into the thermal resistance  $R_{case-ambient}$  at this point. Thus, the following formula is also used:

$$T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot P_d + T_{ambient}$$